

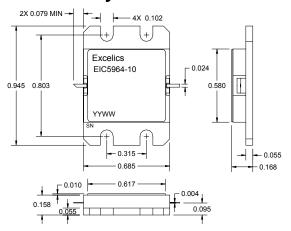
EIC5964-10

UPDATED 08/21/2007

5.90-6.40 GHz 10-Watt Internally Matched Power FET

FEATURES

- 5.90-6.40GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +40.5 dBm Output Power at 1dB Compression
- 10.0 dB Power Gain at 1dB Compression
- 37% Power Added Efficiency
- -46 dBc IM3 at PO = 29.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS (T_a = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 5.90-6.40GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 3200\text{mA}$	39.5	40.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 5.90-6.40GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 3200\text{mA}$	9.0	10.0		dB
ΔG	Gain Flatness $f = 5.90-6.40$ GHz $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 3200$ mA			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 3200mA f = 5.90-6.40GHz		37		%
ld₁ _{dB}	Drain Current at 1dB Compression f = 5.90-6.40GHz		3200	3600	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 29.5 dBm S.C.L ² V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS f = 6.40GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		5800	6400	mA
V _P	Pinch-off Voltage V _{DS} = 3 V, I _{DS} = 60 mA		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		2.5	3.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS PARAMETERS		ABSOLUTE ¹	CONTINUOUS ²	
Vds	Vds Drain-Source Voltage		10V	
Vgs Gate-Source Voltage		-5V	-4V	
lgf	Forward Gate Current	136mA	40.8mA	
lgr	Reverse Gate Current	-27.2mA	-6.8mA	
Pin	Input Power	40dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg Storage Temperature		-65C to +175C	-65C to +175C	
Pt Total Power Dissipation		50W	50W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

^{2.} S.C.L. = Single Carrier Level.

^{3.} Overall Rth depends on case mounting.

^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.

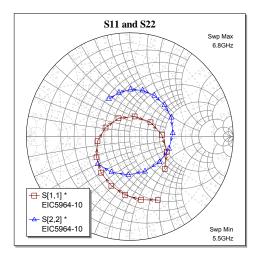


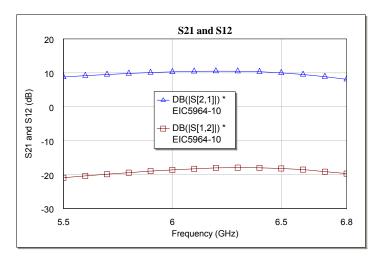
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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} \approx 3200mA





FREQ	S	11	S21		S12		S	22
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5.00	0.842	-10.380	2.138	85.680	0.066	23.190	0.279	-146.210
5.25	0.770	-36.270	2.452	52.620	0.075	-8.650	0.338	160.980
5.50	0.668	-66.150	2.749	17.860	0.090	-42.660	0.414	119.050
5.75	0.535	-102.210	3.044	-18.590	0.104	-77.630	0.459	82.070
6.00	0.378	-148.060	3.268	-57.830	0.118	-116.340	0.453	42.110
6.25	0.226	142.100	3.354	-99.660	0.126	-157.830	0.407	-5.740
6.50	0.243	34.670	3.165	-144.200	0.123	159.460	0.366	-66.250
6.75	0.423	-32.680	2.662	171.730	0.107	116.550	0.395	-128.840
7.00	0.573	-76.790	2.037	131.380	0.084	77.710	0.470	-176.150
7.25	0.675	-110.330	1.498	95.780	0.066	45.490	0.549	151.630
7.50	0.750	-137.290	1.090	64.300	0.050	12.690	0.624	128.540

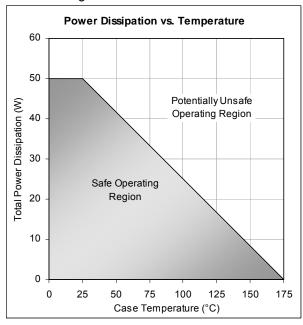


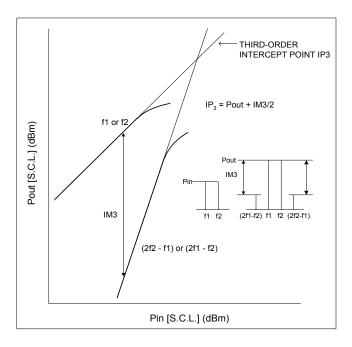


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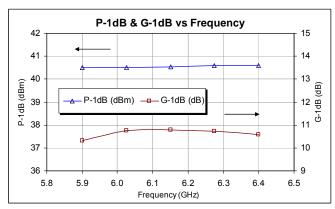
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Power De-rating Curve and IM3 Definition

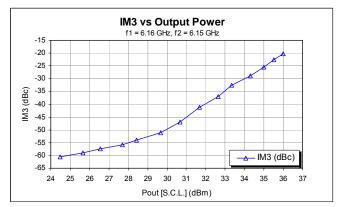




Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 3200 mA)



Typical IM3 Data (V_{DS} = 10 V, I_{DSQ} ≈ 65% IDSS)





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ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC5964-10	Hermetic	Industrial	5.90-6.40GHz	39.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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